SHARP

PC923X

OPIC Photocoupler

High Speed OPIC Photocoupler for MOS-FET/IGBT Drive

Features

(1) Built-in direct drive circuit for MOS-FET/IGBT drive

(Io1P, Io2P: 0.4 A)
(2) High speed response
(tphl,tplh: MAX. 0.5 μs)

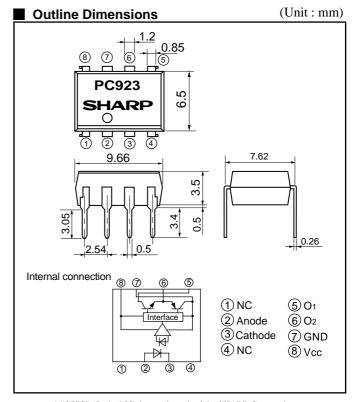
(3) Wide operating supply voltage range (Vcc: 15 to 30 V, Ta= -10 to 60 $^{\circ}$ C)

(4) High noise reduction type (CMH=MIN. -1 500 V/ μ s) (CML=MIN. 1 500 V/ μ s)

(5) High isolation voltage (Viso(rms): 5 kV)

Applications

(1) Inverter controlled air conditioners



^{* &}quot;OPIC" (Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.

Absolute Maximum Ratings

(Unless specified, Ta=Topr)

Parameter			Symbol	Ratings	Unit
T	Forward	d current	IF	20	mA
Input	*1 Reverse	voltage	VR	6	V
Output	Supply	voltage	Vcc	35	V
	O1 Output	current	Ioı	0.1	A
	*2 O ₁ Peak ou	tput current	Іоір	0.4	A
	O2 Output	current	Io2	0.1	A
	*2 O2 Peak ou	tput current	I _{O2P}	0.4	A
	O1 Output	voltage	Voi	35	V
	Power d	lissipation	Po	500	mW
	Total po	ower dissipation	Ptot	550	mW
	*3 Isolation	n voltage	V _{iso(rms)}	5.0	kV
	Operation	ng temperature	Topr	-20 to +80	°C
	Storage	temperature	Tstg	-55 to +125	°C
	*4 Solderin	ng temperature	Tsol	260	°C

- *1 Ta=25°C
- *2 Pulse width $\leq 0.15 \,\mu\text{s}$, duty ratio= 0.01
- *3 40 to 60% RH, AC for 1 minute, Ta=25°C
- *4 For 10s

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■ Electro-optical Characteristics

(Unless specified, Ta=Topr)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	F 1 1/2	V_{F1}	T _a = 25 °C, I _F =10 mA	-	1.6	1.75	V
Input	Forward voltage	V_{F2}	T _a = 25 °C, I _F = 0.2 mA	1.2	1.5	-	V
	Reverse current	IR	T _a = 25 °C, V _R = 5 V	_	_	10	μΑ
	Terminal capacitance	Ct	T _a =25 °C, V= 0, f= 1 kHz	-	30	250	pF
		Vcc	T _a = -10 to 60 °C	15	_	30	V
	Operation temperature supply voltage		-	15	_	24	V
	O1 low level output voltage	Voil	V _{CC1} =12 V, V _{CC2} = -12 V, I _{O1} = 0.1 A, I _F = 5 mA	-	0.2	0.4	V
	O2 high level output voltage	V _{O2H}	Vcc=Vo1= 24 V, Io2= -0.1 A, IF= 5 mA	18	21	-	V
Output	O2 low level output voltage	V _{O2L}	Vcc= 24 V, Io2= 0.1 A, I _F = 0	_	1.2	2.0	V
_	O1 leak current	Ioil	Ta= 25 °C,Vcc=Voi= 35 V, IF=0 mA	_	_	500	μΑ
	O2 leak current	IO2L	Ta= 25 °C,Vcc=Vo2= 35 V, I _F =5 mA	_	_	500	μΑ
	TT: 1 1 1 1	Іссн	T _a =25 °C, V _{CC} = 24 V, I _F = 5 mA	_	6	10	mA
	High level supply current		Vcc= 24 V, I _F = 5 mA	_	_	14	mA
	Low level supply current	Iccl	T _a =25 °C, V _{CC} = 24 V, I _F = 0 mA	_	8	13	mA
	Low level supply current		Vcc= 24 V, I _F = 0 mA	_	_	17	mA
Transfer characteristics	"Low→High" thresh hold	IFLH	T _a =25°C, V _{CC} = 24 V	0.3	1.5	3.0	mA
	input current *5		Vcc= 24 V	0.2	-	5.0	mA
	Isolation resistance	Riso	T _a = 25 °C, DC= 500 V 40 to 60 %RH	5 x 10 ¹⁰	1 x 10 ¹¹	-	Ω
	≝ "Low→High"transfer time	tplh		-	0.3	0.5	μs
	"Low→High"transfer time "High→Low"transfer time Rise time Fall time	t PHL	$T_a = 25 ^{\circ}\text{C}$, $V_{CC} = 24 \text{V}$, $I_F = 5 \text{mA}$,	-	0.3	0.5	
	Rise time	tr	$R_G=47 \Omega$, $C_G=3000 pF$	_	0.2	0.5	
	වූ Fall time	tr		_	0.2	0.5	
	Instantaneous common mode rejection voltage "Output:High level"	СМн	Ta=25 °C, Vcm=600 V(peak), IF=5 mA Vcc= 24 V, ΔVo2H= 2.0 V	-1 500	_	-	V/µs
	Instantaneous common mode rejection voltage "Output: Low level"	CML	Ta=25 °C, V _{CM} =600 V _(peak) , I _F = 0 mA V _{CC} = 24 V, ΔV _{O2} L= 2.0 V	1 500	-	_	V/µs

^{*5} Iflh is forward current when output O_2 become "Low" to "High"

Truth Table

Input	O ₂ output	Tr. 1	Tr. 2
ON	High level	ON	OFF
OFF	Low level	OFF	ON

^{*6} When measuring output and transfer characteristics, connect a by-pass capacitor (0.01 μ F or more) between VCC and GND near the device.

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